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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

18 papers	189 citations	7 h-index	13 g-index
20 ext. papers	213 ext. citations	3.1 avg, IF	2.97 L-index

#	Paper	IF	Citations
18	Predicting Microstructure Evolution During Directed Energy Deposition Additive Manufacturing of Ti-6Al-4V. <i>Journal of Manufacturing Science and Engineering, Transactions of the ASME</i> , 2018 , 140,	3.3	39
17	Particle-size and morphology dependence of the preferred interface orientation in LiFePO ₄ nano-particles. <i>Journal of Materials Chemistry A</i> , 2014 , 2, 15437-15447	13	37
16	The thermodynamic stability of intermediate solid solutions in LiFePO ₄ nanoparticles. <i>Journal of Materials Chemistry A</i> , 2016 , 4, 5436-5447	13	26
15	Grain boundary grooving and cathode voiding in bamboo-like metallic interconnects by surface drift diffusion under the capillary and electromigration forces. <i>Journal of Applied Physics</i> , 2005 , 97, 093520	2.5	23
14	Morphological evolution of voids by surface drift diffusion driven by capillary, electromigration, and thermal-stress gradients induced by steady-state heat flow in passivated metallic thin films and flip chip solder joints. I. Theory. <i>Journal of Applied Physics</i> , 2008 , 104, 023521	2.5	12
13	Cathode edge displacement by voiding coupled with grain boundary grooving in bamboo like metallic interconnects by surface drift-diffusion under the capillary and electromigration forces. <i>International Journal of Solids and Structures</i> , 2008 , 45, 921-942	3.1	9
12	A process-microstructure finite element simulation framework for predicting phase transformations and microhardness for directed energy deposition of Ti6Al4V. <i>Additive Manufacturing</i> , 2020 , 35, 101252	6.1	7
11	Grain boundary grooving induced by the anisotropic surface drift diffusion driven by the capillary and electromigration forces: Simulations. <i>Journal of Applied Physics</i> , 2011 , 110, 043521	2.5	7
10	Grain boundary grooving in bi-crystal thin films induced by surface drift-diffusion driven by capillary forces and applied uniaxial tensile stresses. <i>Philosophical Magazine</i> , 2012 , 92, 804-829	1.6	7
9	Mesoscopic nonequilibrium thermodynamics treatment of the grain boundary thermal grooving induced by the anisotropic surface drift diffusion. <i>Journal of Materials Science</i> , 2011 , 46, 6054-6064	4.3	5
8	Morphological evolution of voids by surface drift diffusion driven by the capillary, electromigration, and thermal-stress gradient induced by the steady state heat flow in passivated metallic thin films and flip-chip solder joints. II. Applications. <i>Journal of Applied Physics</i> , 2008 , 104, 023522	2.5	4
7	Morphological evolution of tilted grain-boundary thermal grooving by surface diffusion in bicrystal thin solid films having strong anisotropic surface Gibbs free energies. <i>Journal of Applied Physics</i> , 2008 , 104, 013518	2.5	4
6	Thermal Grooving by Surface Diffusion: a Review of Classical Thermo-Kinetics Approach. <i>Hittite Journal of Science & Engineering</i> , 2017 , 4, 7-16	1	4
5	Synthesis, characterization and electrochemical performance of Nb doped LiFePO ₄ /C cathodes. <i>Hittite Journal of Science & Engineering</i> , 2018 , 5, 49-55	1	2
4	Computer Simulations on the Grain Boundary Grooving and Cathode Edge Displacement in Bamboo-like Metallic Interconnects. <i>Materials Research Society Symposia Proceedings</i> , 2006 , 914, 1		1
3	YKSEK KROMLU BEYAZ DİME DEMİRLERDE FAZ DENGESİNİN BENZETİMİ <i>Uludağ University Journal of the Faculty of Engineering</i> , 2018 , 23, 179-190	0.1	1
2	Influence of displacement constraints to the surface reconstruction of stressed bicrystal thin films. <i>Materials Research Express</i> , 2020 , 7, 026411	1.7	

- 1 Morphological Evolution of Intragranular Void under the Thermal-Stress Gradient Generated by the Steady State Heat Flow in Encapsulated Metallic Films: Special Reference to Flip Chip Solder Joints. *Solid State Phenomena*, **2008**, 139, 151-156 0.4